

Multi-Layer Nanoelectromechanical (NEM) Memory

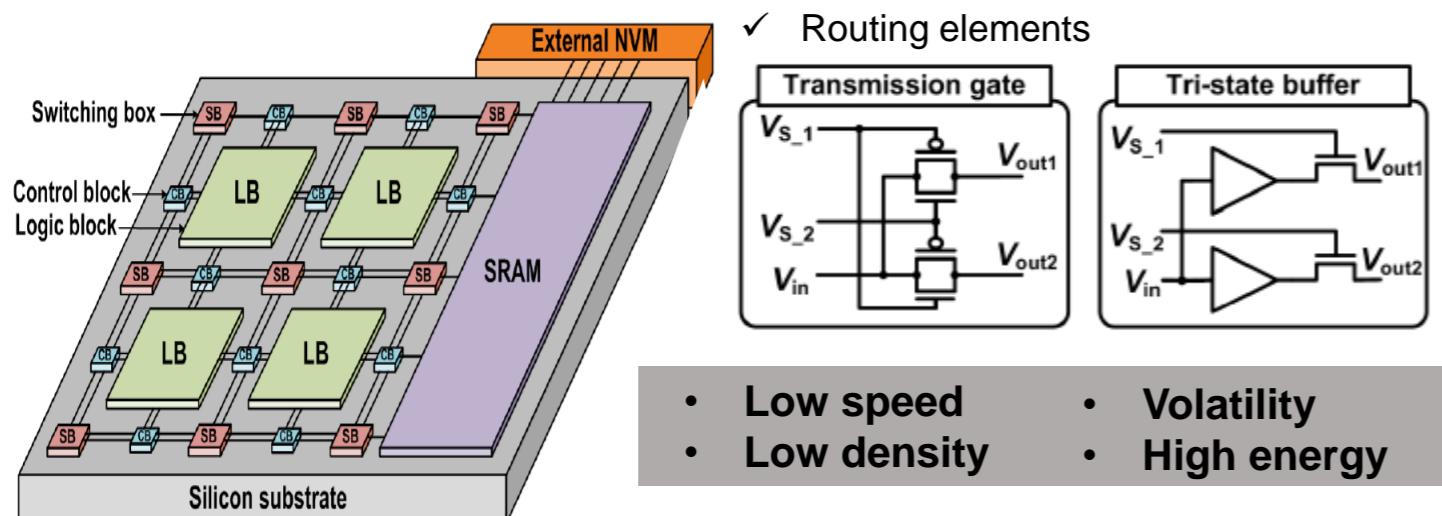
Switches for Efficient Routing Operation

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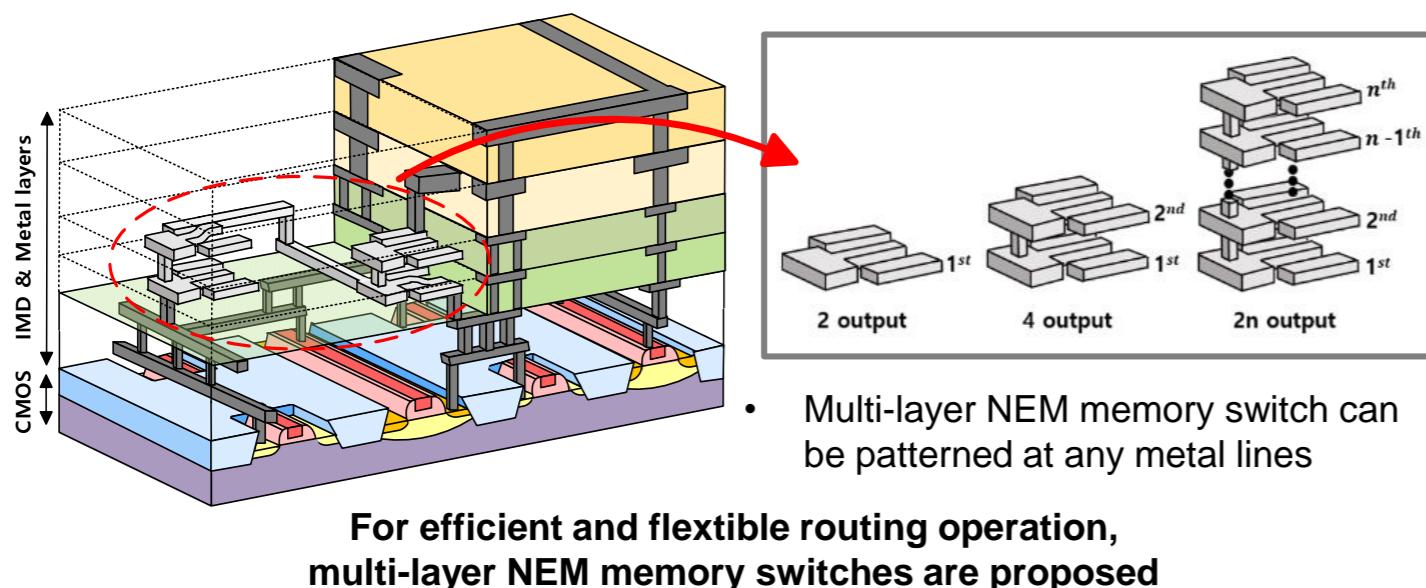
Motivation (1)

- RL such as FPGA, CPLD consists of logic blocks and routing elements
- In conventional RL case, routing operation consumes ~ 80% of chip area, ~ 80% of core power and ~ 75% total delay



Need to decrease chip area, power consumption and delay

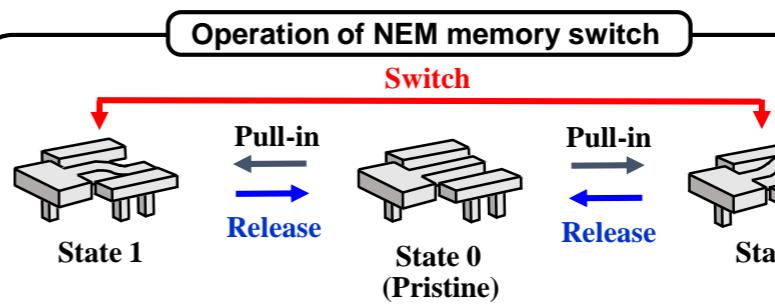
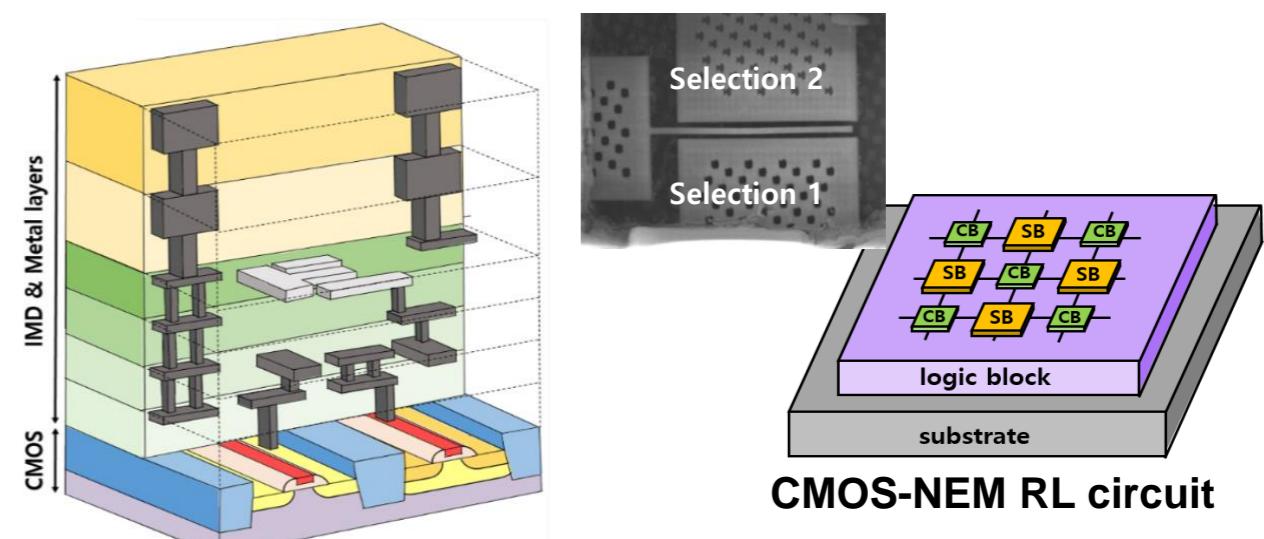
Ideas



- Multi-layer NEM memory switch can be patterned at any metal lines

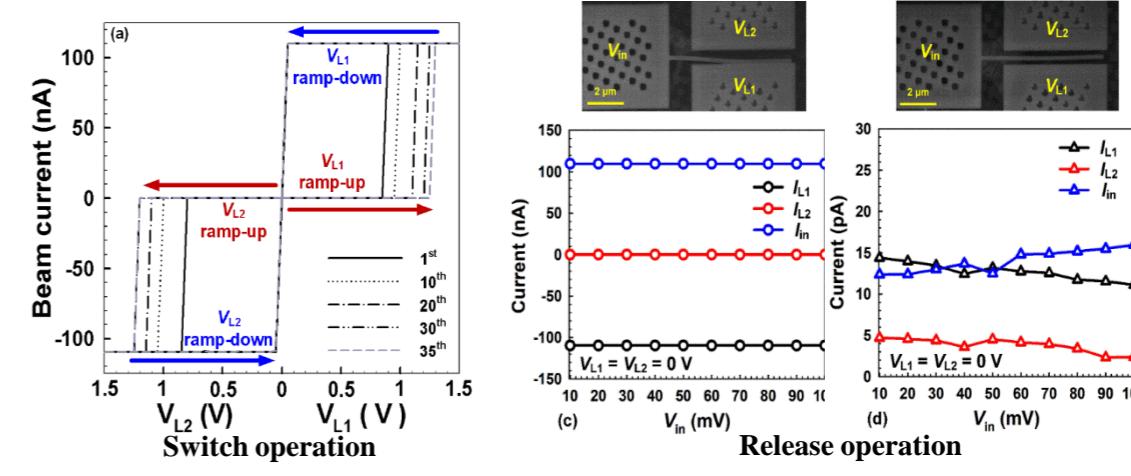
Motivation (2)

- Replace routing elements from CMOS-only to NEM memory switch at single metal layer
- Routing elements located at BEOL

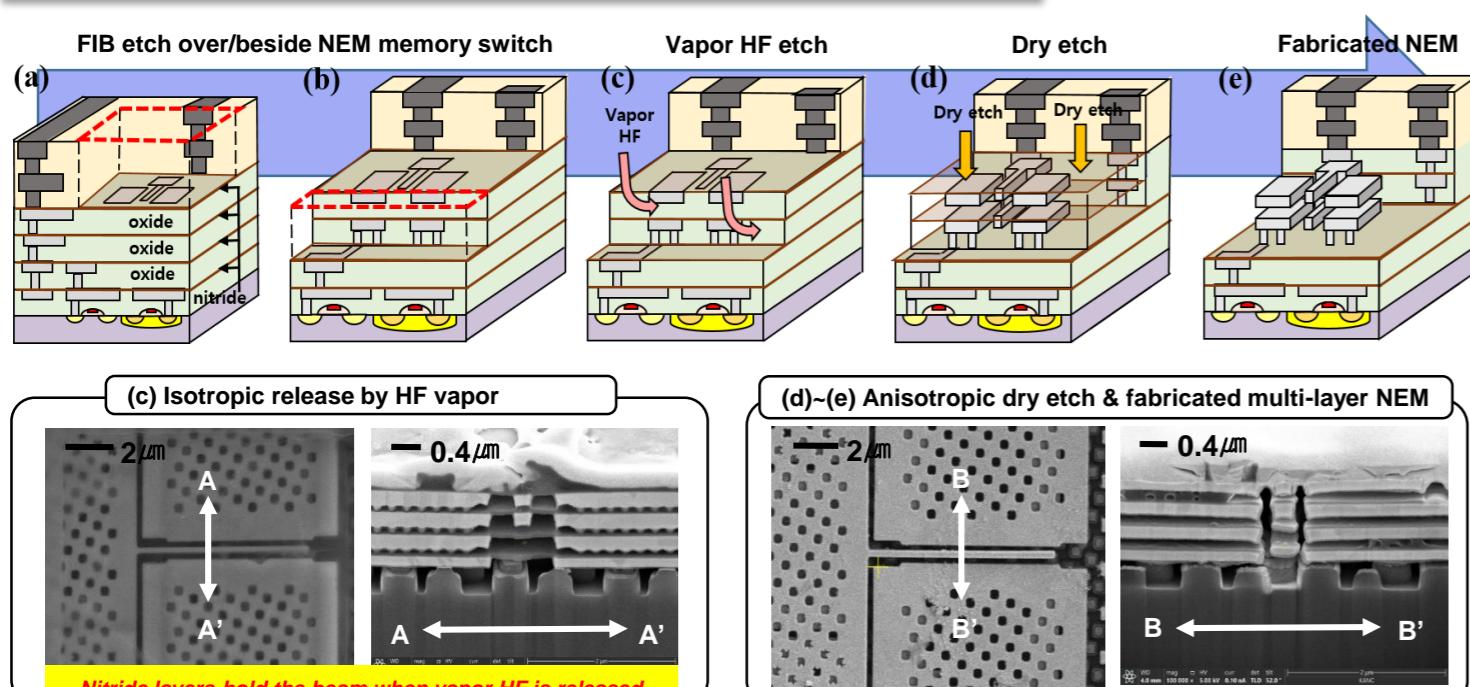


- High speed
- High density
- Non-Volatility
- Low energy

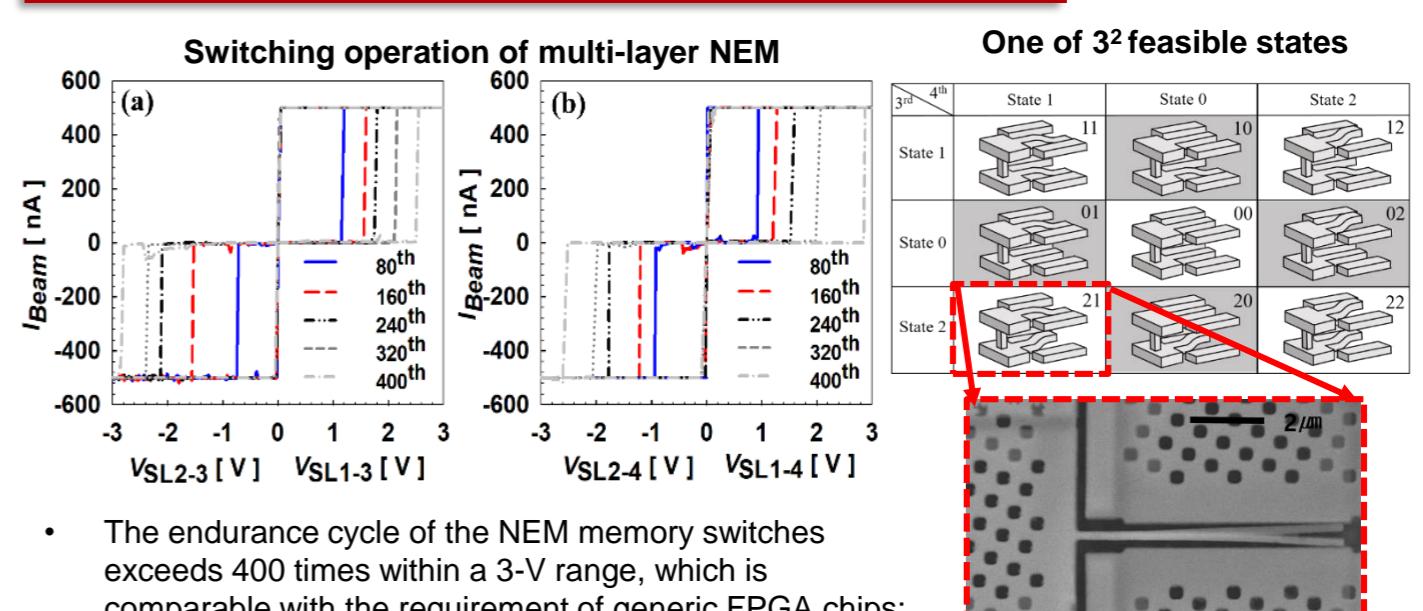
Experimental results of operation



Fabrication process



Experimental Results



- The endurance cycle of the NEM memory switches exceeds 400 times within a 3-V range, which is comparable with the requirement of generic FPGA chips: ~500 times.

Conclusion

- Multi-layer NEM memory switches integrated vertically over CMOS baseline circuits were experimentally demonstrated using a 65-nm CMOS baseline process
- By fabrication process, the throughput of NEM memory switch is increased than before process.
- The area, energy and power of multi-layer NEM memory switches are superior to CMOS-only routing elements
- An n -layer NEM memory switches can implement 3^n states which can be used for a $2n$ -to-1 multiplexer or 1-to- $2n$ de-multiplexer

Simulation Results

